

Supporting Information

Bulk and Interfacial Engineering of Ta₃N₅ Nanotube Arrays by Sn(IV) Doping, Proper Passivation and Co-Catalyst for Efficient Solar Water Oxidation

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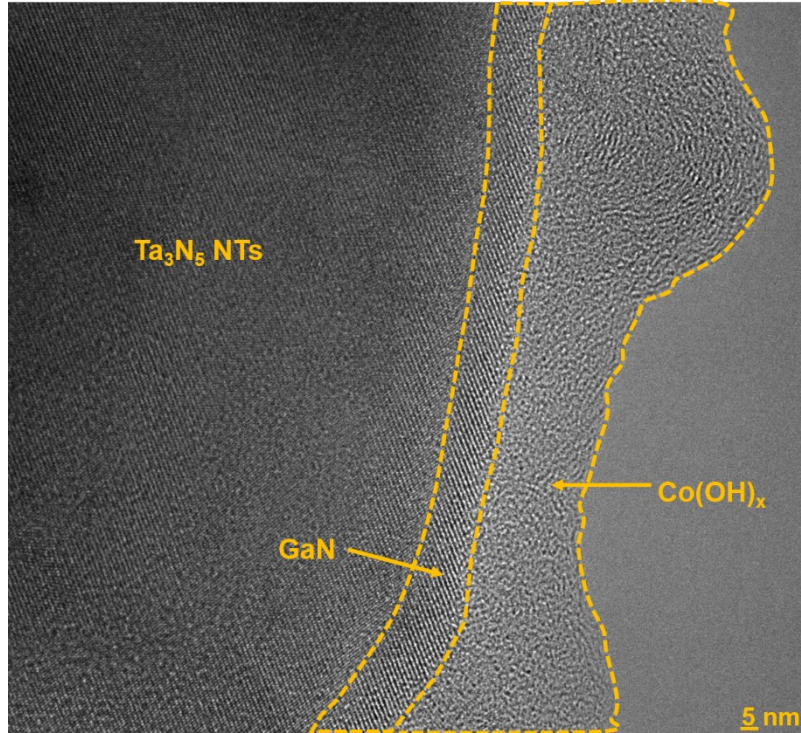


Figure S1. Bright-field (HAADF-TEM) image representing the interfaces in the Co(OH)_x/GaN/Sn doped Ta₃N₅ NTs film.

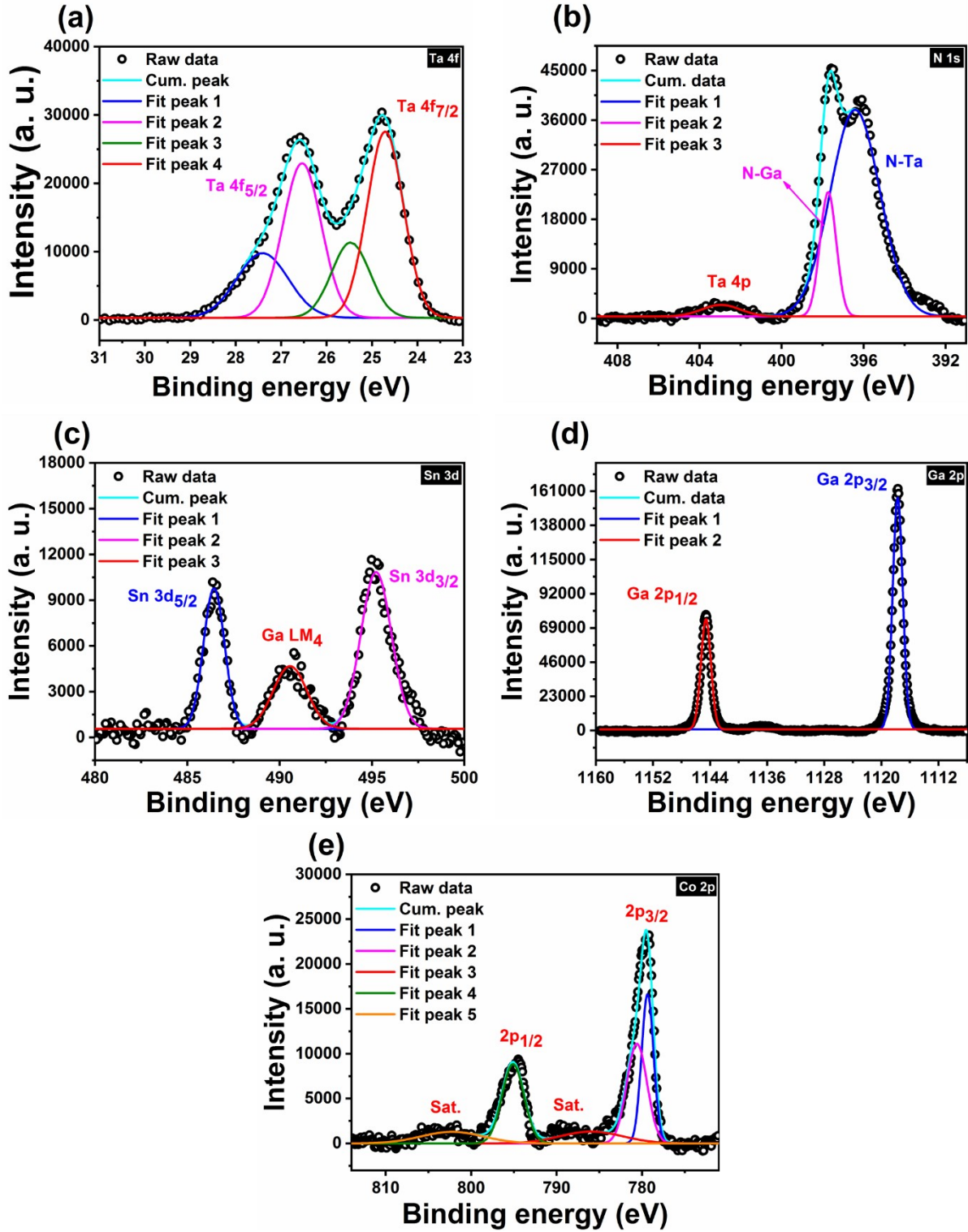


Figure S2. Core-level XPS spectra of (a) Ta4f, (b) N1s, (c) Sn3d, (d) Ga2p, and (e) Co2p of Co(OH)_x/GaN/Sn doped Ta₃N₅ NTs film after the PEC test.

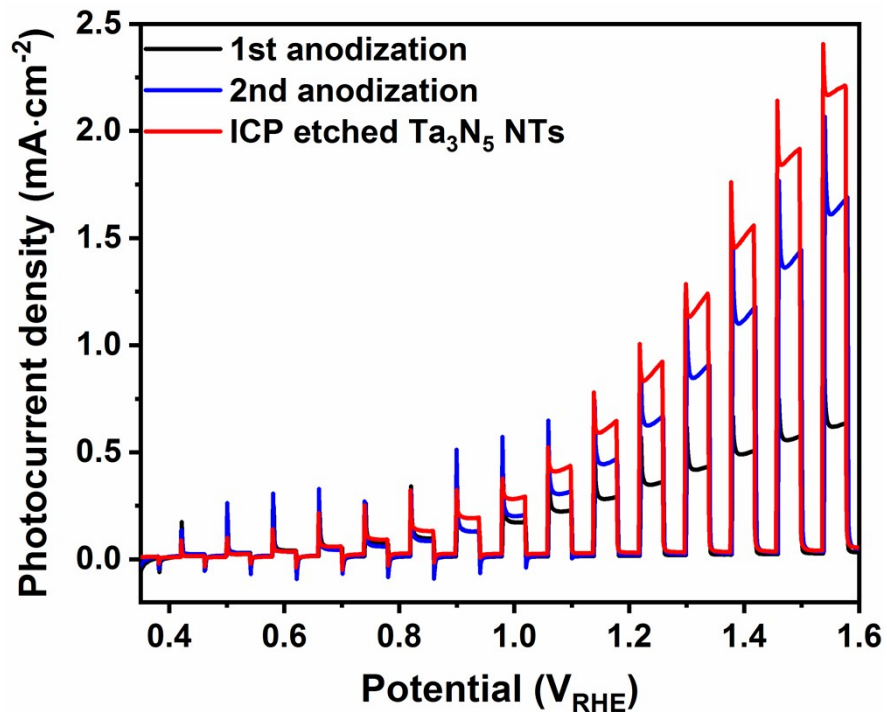


Figure S3. Chopped LSV curves of 1st and 2nd anodization and ICP etched of bare Ta₃N₅ NTs films.

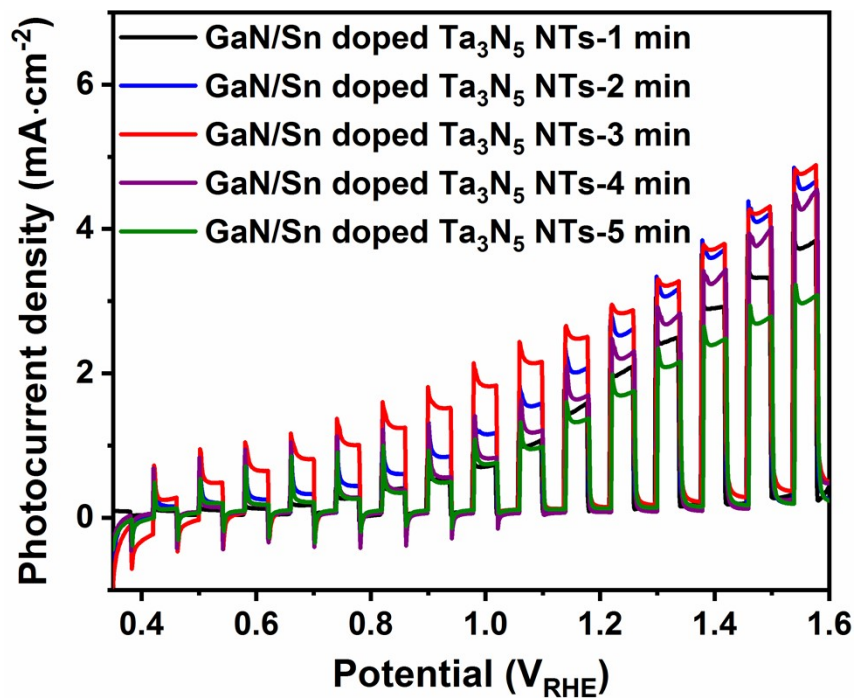


Figure S4. Chopped LSV curves of GaN/Sn doped Ta₃N₅ NTs films at different electrodeposition times from 1min to 5min by chronoamperometric method.

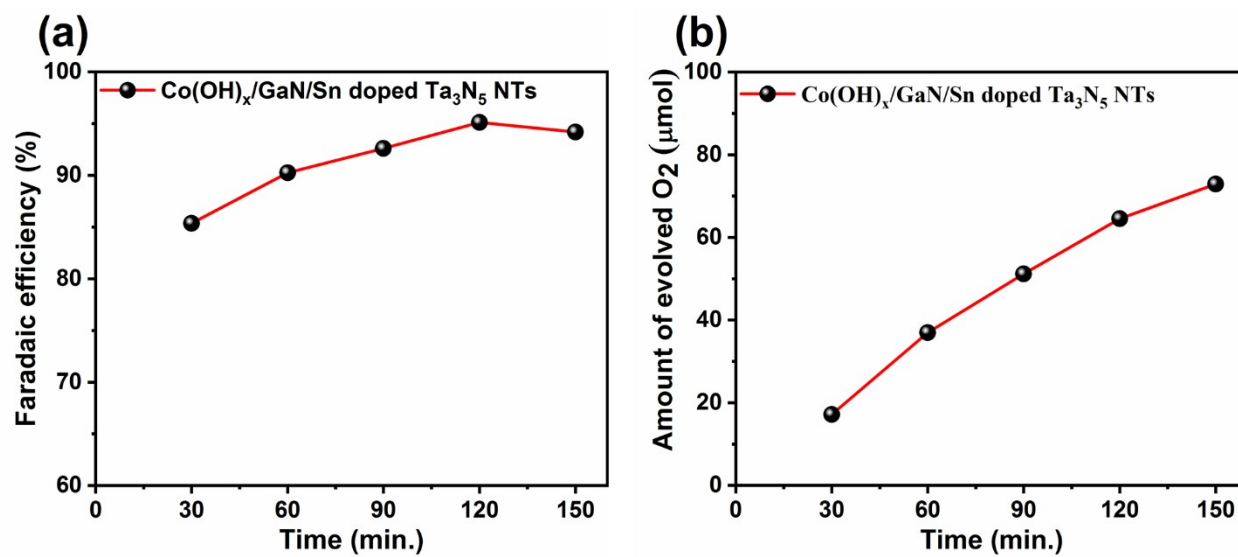


Figure S5. (a) Faradaic efficiency and (b) quantities of the detected O₂ gas in a PEC system from the Co(OH)_x/GaN/Sn doped Ta₃N₅ NTs photoanode as the working electrode under applied voltages of 1.23 V_{RHE} in 0.5 M NaOH solution at pH 12.5.

Table S1. The previous reported Ta₃N₅-based photoanodes are compared in below Table.

Material	Fabrication Method	Surface Modification	IPCE & J (mA/cm²) at 1.23 V_{RHE}	Ref.
Ba doped Ta ₃ N ₅	Mask anodization and nitridation of Ta foil	Co-Pi	6.7 mA cm ⁻² (0.5 M KPi)	41
Mg-Zr codoped Ta ₃ N ₅	Particle transfer	FeO _x + CoO _x	2.3 mA cm ⁻² (0.1 M Na ₂ SO ₄)	79
Ta ₃ N ₅	Hydrothermal and nitridation of Ta foil	Co(OH) ₂ /Co ₃ O ₄	3.64 mA cm ⁻² (1 M NaOH)	80
Ta ₃ N ₅	Hydrothermal and nitridation of Ta foil	Co(OH) _x	2.8 mA/cm ² (1 M NaOH)	81
Ta ₃ N ₅	Sputtering and nitridation of TaO ₅ on Ta substrate	GaN/Co-Pi	8 mA cm ⁻² at 1.2 V _{RHE} (0.5 M KPi)	52
Ta ₃ N ₅	Electrophoretic deposition	Co ₃ O ₄ /Co(OH) _x	3.18 mA/cm ² at 1.2 V _{RHE} (1 M NaOH)	82
Ta ₃ N ₅	Anodization and nitridation of Ta foil	MgO/Co(OH) _x	5.5 mA cm ⁻² (1 M NaOH)	83
Ta ₃ N ₅	Anodization, hydrothermal and nitridation of Ta foil	Ni(OH) _x /Fh/TiO _x	12.1 mA cm ⁻² (1 M NaOH)	49
Ta ₃ N ₅	Sputtering (magnetron GLAD system)	FeNiO _x	9.95 mA cm ⁻² at 1.05 V _{RHE} (0.5 M K ₂ HPO ₄)	53
In:GaN/Ta ₃ N ₅ /Mg:GaN	Electron beam evaporation, atomic layer deposition and nitridation	NiCoFe-B _i	9.3 mA cm ⁻² (1 M KOH)	54
Mg doped Ta ₃ N ₅	Electron beam evaporation and nitridation	NiCoFe-B _i	8.5 mA cm ⁻² (1 M KOH)	84
Sn doped Ta₃N₅	Anodization and nitridation of Ta foil, electrodeposition	GaN/Co(OH)_x	39%, 4.58 mA cm⁻² (0.5 M NaOH)	This work